

ABSTRACT

5 A polishing method capable of improving flatness of a bonding surface for forming
a laminated substrate is disclosed. The polishing method includes: measuring a shape of
a periphery of a substrate having the bonding surface for forming the laminated substrate,
the bonding surface including a surface of a device region and a surface of a dielectric film
formed on the periphery and raised from the device region; determining a polishing recipe
10 including a change in a movement speed of a polishing head from a polishing start position
to a polishing end position based on the measured shape of the periphery; and polishing the
dielectric film to planarize the bonding surface by pressing, by the polishing head, a
polishing tool against the periphery of the substrate being rotated while the polishing head
is moved in a radial direction of the substrate according to the determined polishing recipe.

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FIG. 5